I’d like to welcome the newest addition to the FlexTech team, Dr. Stefanie Harvey. Stefanie has joined the team as our R&D program manager and will provide technical and organizational oversight of our R&D consortia collaborating with our project teams from academia, industry and government organizations. Stefanie brings an impressive set of skills to our technology community having experience in semiconductor equipment, process engineering, and smart materials for applications in electronics, biotechnology, and aerospace industries.

In other news, I am happy to announce the launch of the FlexTech InfoHub this month. Use the InfoHub as a resource to access information about the flexible electronics industry. We welcome any feedback about the new site along with information regarding flexible electronics news, articles, upcoming events and technical material you would like us to add to the site.

And finally, FLEX 2019— our flagship flexible and printed electronics conference— has open their Call for Abstracts. Please take a look at the website for more information about topic areas and guidelines.

Sincerely,

Dr. Melissa Gruen-Shemansky
Executive Director & CTO

News and Announcements

Announcing the FlexTech InfoHub

This month, we launched the new FlexTech InfoHub, a central portal dedicated to flexible, hybrid and printed electronics technology. The website is designed as a powerful educational platform and resource for the technical community as well as the general audience to easily find out more about the technology and what it means for electronics.

The FlexTech InfoHub features a main home page that graphically outlines the various sections:

- About FlexTech
- Projects
- Public Library
- Members Only
Highlighted Events

Within the pages, visitors can expect to learn about FlexTech, the ongoing efforts of the flexible electronics R&D program—including past and present projects, project calls and more. The Public Library page contains the member directory, news on flexible electronics, standards and more content. Access to the specific pages for more information are available from the sticky sub-menu.

Check Out the New InfoHub

FLEX 2019 - Call for Abstracts

Flexible Hybrid Electronics (FHE) are high-performance, integrated devices. Curved and variable in form factor, they augment day-to-day life with diverse applications, enabling us to interact with our surroundings like no personal computing devices have ever before.

As new methods for creating them emerge, business and supply chain paradigms are increasingly challenged. That's what *Building Outside the Box* is all about: Speakers will highlight the latest technology breakthroughs and business strategies, and provide informative demonstrations of flexible hybrid and printed electronics products, equipment, and materials, as well as the unique electronics applications they enable.

The FLEX 2019 conference provides a great opportunity to highlight your expertise before hundreds of professionals from across the industry's extended value chain. Please consider giving a presentation on your personal contribution to FHE innovation and the impact it is having on the future of electronics.

Submit an abstract before SEPTEMBER 15, 2018 for the opportunity to present at FLEX 2019 as a leader in this up-and-coming technology.

Join the FlexTech Standards Effort!

On the newly released FlexTech InfoHub, we have a section dedicated to the ongoing standards efforts within the flexible, hybrid and printed electronics community. This is by no mean a conclusive list and will be updated as more relevant standards are identified. Standards organizations include:

- SEMI Standards
- IPC Standards
- IEC Standards
- ISO Standards
- ASTM Standards
- TAPPI Standards

Join our flexible electronics standards initiative! By participating, you are a part of the bigger picture and setting the expectations for developments in years to come. Contact us at FHEstandards@semi.org to get started.

FlexTech Webinars

Watch and download past webinars on the Members Only community.
Technology Communities News Round Up

MEMS & Sensors Industry Group

- Discover what's happening in Taiwan's MEMS and Sensors industry at the SEMICON Taiwan's MEMS and Sensors Forum.
- Stay up-to-date with developments in Europe at the European MEMS & Sensors & Imaging Summit.

Fab Owners Alliance

- Read a recap of the FOA Q2 meeting in Fort Collins, Colorado.

Upcoming Events

WEBINAR: Overview of the 5G New Radio Physical Layer
AUGUST 7, 2018
8:00 AM - 9:00 AM PDT

What makes 5G possible?
Overview of the 5G New Radio Physical Layer

NOVEMBER 13-14, 2018

Register Now!

FLEX 2019
Monterey, California, USA
FEBRUARY 18-21, 2019

Exhibit Booths Now Available!

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